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(71) Applicant: **KNOWLES ELECTRONICS, LLC**
[US/US], 1151 Maplewood Drive, Itasca, IL 60143 (US)

(72) Inventor: **MINERVINI, Anthony, D.**, 11263 Westwood
Drive, Palos Hills, IL 60465 (US).

(74) Agent: **MORNEAULT, Monique, A.**, Wallenstein &
Wagner, Ltd., 311 South Wacker Drive - 5300, Chicago,
IL 60606 (US).

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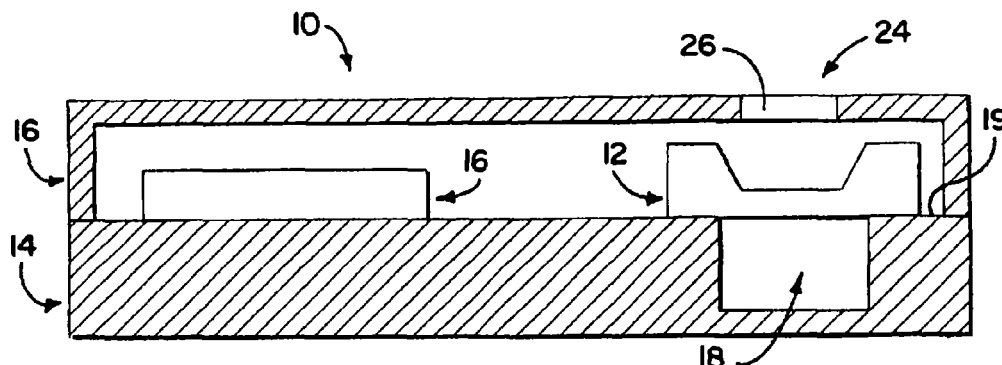
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(54) Title: MINIATURE SILICON CONDENSER MICROPHONE AND METHOD FOR PRODUCING SAME



(57) Abstract: A silicon condenser microphone package is disclosed. The silicon condenser microphone package comprises a transducer unit, a substrate, and a cover. The substrate includes an upper surface having a recess formed therein. The transducer unit is attached to the upper surface of the substrate and overlaps at least a portion of the recess wherein a back volume of the transducer unit is formed between the transducer unit and the substrate. The cover is placed over the transducer unit and includes an aperture

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